

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Prior Application: J. TANAKA et al et al  
Serial No. 10/179,214  
Filed: June 26, 2002

Group Art Unit: 2815  
Examiner: S. Clark  
For: RESIN-ENCAPSULATED SEMICONDUCTOR  
APPARATUS AND PROCESS FOR ITS  
FABRICATION

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
Alexandria, VA 22314

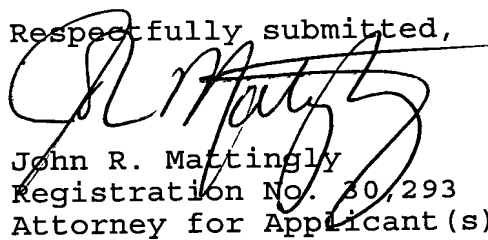
Sir:

In accordance with the duty of disclosure, Applicants inform the Examiner of the documents cited during prosecution of the parent application, USSN 10/179,214.

This is a continuation application of U.S. Serial No. 10/179,214, filed on June 26, 2002, which is a continuation application of U.S. Serial No. 09/969,847, filed October 4, 2001, now U.S. Patent No. 6,465,827, which is a continuation application of U.S. Serial No. 09/689,802, filed October 13, 2000, now U.S. Patent No. 6,441,416, which is a continuation application of U.S. Serial No. 09/665,062, filed September 19, 2000, abandoned, which is a divisional application of U.S. Serial No. 09/012,104, filed January 22, 1998, now U.S. Patent No. 6,147,374. This application is related to application Serial No. 09/969,848, filed October 4, 2001, now U.S. Patent No. 6,525,359, from which priority is claimed under 35 U.S.C. § 120.

The applicants request the Examiner to initial and return a copy of the attached PTO-1449 form as an indication that the references have been considered.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "J. Mattingly", is written over the typed name and registration information.

John R. Mattingly  
Registration No. 30,293  
Attorney for Applicant(s)

MATTINGLY, STANGER & MALUR  
1800 Diagonal Road, Suite 370  
Alexandria, Virginia 22314  
(703) 684-1120  
Date: September 29, 2003

|   |    |  |          |                                  |       |               |   |
|---|----|--|----------|----------------------------------|-------|---------------|---|
| FORM PTO-1449<br>(REV. 7-80)  |    | U.S. DEPARTMENT OF COMMERCE<br>PATENT AND TRADEMARK OFFICE   |          | ATTY. DOCKET NO.<br>HIT 2 925-08 |       | SERIAL NO.    |   |
| <b>LIST OF DOCUMENTS CITED BY APPLICANT</b><br><i>(Use several sheets if necessary)</i>   |    |  |          | APPLICANT<br>J. TANAKA et al     |       |               |   |
|   |    |  |          | FILING DATE<br>09/29/03          |       | GROUP<br>2815 |   |
| <b>U.S. PATENT DOCUMENTS</b>  |    |  |          |                                  |       |               |   |
| * EXAMINER<br>INITIAL   |    | DOCUMENT   | DATE     | NAME                             | CLASS | SUBCLASS      | FILING DATE<br><i>(If Appropriate)</i>            |
|   | AA | 5,563,762  | 10/1996  | Leung et al                      |       |               |   |
|   | AB | 5,117,272  | 05-1992  | Nomura et al                     |       |               |   |
|   | AC | 5,310,863  | 05-1994  | Sachdev                          |       |               |   |
|   | AD | 6,071,755  | 06-2000  | Baba et al                       |       |               |   |
|   | AE | 6,106,906  | 08-2000  | Matsuda et al                    |       |               |   |
|   | AF | 5,296,716  | 03-1994  | Ovashinsky et al                 |       |               |   |
|   | AG | 4,132,823  | 1/2/79   | Blackwell et al                  |       |               |   |
|   | AH | 6,465,827  | 10/2002  | Tanaka et al                     |       |               |   |
|   | AI |  |          |                                  |       |               |   |
|   | AJ |  |          |                                  |       |               |   |
|   | AK |  |          |                                  |       |               |   |
| <b>FOREIGN PATENT DOCUMENTS</b>   |    |  |          |                                  |       |               |   |
|   |    | DOCUMENT   | DATE     | COUNTRY                          | CLASS | SUBCLASS      | TRANSLATION<br>YES NO                             |
|   | AL | 8-124917   | 05-1996  | Japan                            |       |               | <input type="checkbox"/> <input type="checkbox"/> |
|   | AM | 7-278301   | 10-1995  | Japan                            |       |               | <input type="checkbox"/> <input type="checkbox"/> |
|   | AN | 07-221259  | 8/18/95  | Japan                            |       |               | <input type="checkbox"/> <input type="checkbox"/> |
|   | AO | 09-293837  | 11/11/97 | Japan                            |       |               | <input type="checkbox"/> <input type="checkbox"/> |
|   | AP |  |          |                                  |       |               | <input type="checkbox"/> <input type="checkbox"/> |
| <b>OTHER DOCUMENTS</b> <i>(Including Author, Title, Date, Pertinent Pages, etc.)</i>  |    |  |          |                                  |       |               |   |
|   | AR | Lecture Collections in '96 Ferroelectric Film Memory Technique Forum, Science Forum, Inc., page 4-4, lines 1-12, Ishihara, January 26, 1996.   |          |                                  |       |               |   |
|   | AS | Epoxy Molding Compounds for Semiconductor Devices, Thermosetting Resins, Vol. 13, No. 4, page 37, right column, lines 8-23, Ogata et al, 1992. |          |                                  |       |               |   |
|   | AT | Packaging Technique for Surface Mount Type LSI Packages and Improvements in Its Reliability, page 451, edited by Hitachi, Ltd.                 |          |                                  |       |               |   |
| EXAMINER  |    |  |          | DATE CONSIDERED                  |       |               |   |
| <small>* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small> |    |  |          |                                  |       |               |   |

|   |    |   |      |                                  |       |               |   |
|---|----|---|------|----------------------------------|-------|---------------|---|
| FORM PTO-1449<br>(REV. 7-80)  |    | U.S. DEPARTMENT OF COMMERCE<br>PATENT AND TRADEMARK OFFICE  |      | ATTY. DOCKET NO.<br>HIT 2 925-08 |       | SERIAL NO.    |   |
| <b>LIST OF DOCUMENTS CITED BY APPLICANT</b><br><i>(Use several sheets if necessary)</i>   |    |   |      | APPLICANT<br>J. TANAKA et al     |       |               |   |
|   |    |   |      | FILING DATE<br>09/29/03          |       | GROUP<br>2815 |   |
| <b>U.S. PATENT DOCUMENTS</b>  |    |   |      |                                  |       |               |   |
| * EXAMINER<br>INITIAL   |    | DOCUMENT  | DATE | NAME                             | CLASS | SUBCLASS      | FILING DATE<br><i>(If Appropriate)</i>            |
|   | AA |   |      |                                  |       |               |   |
|   | AB |   |      |                                  |       |               |   |
|   | AC |   |      |                                  |       |               |   |
|   | AD |   |      |                                  |       |               |   |
|   | AE |   |      |                                  |       |               |   |
|   | AF |   |      |                                  |       |               |   |
|   | AG |   |      |                                  |       |               |   |
|   | AH |   |      |                                  |       |               |   |
|   | AI |   |      |                                  |       |               |   |
|   | AJ |   |      |                                  |       |               |   |
|   | AK |   |      |                                  |       |               |   |
| <b>FOREIGN PATENT DOCUMENTS</b>   |    |   |      |                                  |       |               |   |
|   |    | DOCUMENT  | DATE | COUNTRY                          | CLASS | SUBCLASS      | TRANSLATION<br>YES      NO                        |
|   | AL |   |      |                                  |       |               | <input type="checkbox"/> <input type="checkbox"/> |
|   | AM |   |      |                                  |       |               | <input type="checkbox"/> <input type="checkbox"/> |
|   | AN |   |      |                                  |       |               | <input type="checkbox"/> <input type="checkbox"/> |
|   | AO |   |      |                                  |       |               | <input type="checkbox"/> <input type="checkbox"/> |
|   | AP |   |      |                                  |       |               | <input type="checkbox"/> <input type="checkbox"/> |
| <b>OTHER DOCUMENTS</b> <i>(Including Author, Title, Date, Pertinent Pages, etc.)</i>  |    |   |      |                                  |       |               |   |
|   | AR | A Study of Package Cracking During the Reflow Soldering Process, "A" Edition, Vol. 55, No. 510, Kitano et al, 1989-2.   |      |                                  |       |               |   |
|   | AS | Effects of Mold Compound Properties on Lead-on-Chip (LOC) Package Reliability During IR Reflow, 1996 Electronic Components and Technology Conference, Yang et al. |      |                                  |       |               |   |
|   | AT |   |      |                                  |       |               |   |
| EXAMINER  |    |   |      | DATE CONSIDERED                  |       |               |   |
| <small>* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small> |    |   |      |                                  |       |               |   |